

SEA & LAND ELECTRONIC CORP. WWW.SEALAND-PPTC.COM

ALPHA-TOP TECHNOLOGY CORP.

WWW.ALPHA-TOP.COM

APPROVAL SHEET

MODEL NO.:	SMD300L-24V		
CUSTOMER:			
CUSTOMER'S APPR	ROVAL:		
AUTHORIZED SIGN/	ATURE/STAMP:		

DATE

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Submitted by: Approved by:	Chung Cheng YC Lin	
DATE:	23-Jun-21	

SEA & LAND ELECTRONIC CORP.

α 300L 185L 075L α50L

Features Surface Mount Devices Lead free device Size 7.5'5.5 mm 0.29'0.20 inch Surface Mount packaging for automated assembly

Applications Almost anywhere there is a low voltage power supply, up to 60V and a load to be protected, including: Computer mother board, Modem. Telecommunication equipments.

Alpha-Top (Sea & Land Alliance)

SMD300L-24V

Model	V _{max}	I _{max}	l _{hold}	I _{trip}	P _d	Maxir Time T		Resis	Resistance		Agency Approval	
Model	(Vdc)	(A)	@25°C (A)	@25°C (A)	Тур. (W)	Current (A)	Time (Sec)	Ri _{min} (Ω)	R1 _{max} (Ω)	UL	TUV	
SMD300L-24V	24	100	3.00	6.00	1.5	8.0	20.0	0.012	0.048			
hold = Hold Current. trip = Trip Current. M /max = Maximum ope max = Maximum fau Pd = Power dissipat Rimin/max = Minimum	finimum curre rating voltage It current devi ion when devi	nt at which th device can v ce can withst ce is in the tr	ne device will a vithstand witho and without da ipped state in	always trip in 2 out damage at amage at rate 25°C still air e	t rated curre d voltage (V	nt (Imax). max).	e.					

Environmental Specifications

Test	Conditions	Resistance change
Passive aging	+85°C, 1000 hrs.	±5% typical
Humidity aging	+85°C, 85% R.H. , 168 hours	±5% typical
Thermal shock	+85°C to -40°C, 20 times	±33% typical
Resistance to solvent	MIL-STD-202, Method 215	No change
Vibration	MIL-STD-202, Method 201	No change
Ambient operating conditions : - 40 °C to +85 °C		
Maximum surface temperature of the device in the tripped si	tate is 125 °C	

Agency Approvals :

UL pending

Regulation/Standard:



2015/863/EU

EN14582

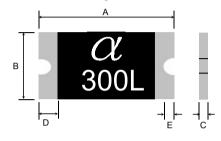
Ihold Versus Temperat	ure								
Model		M	aximum ambi	ient operating	temperature	(T _{mao}) vs. hole	d current (Iho	ld)	
Model	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C
SMD300L-24V	4.53	4.02	3.51	3.00	2.52	2.26	1.99	1.75	1.34

SMD300L-24V

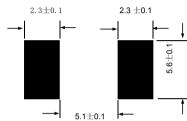
Construction And Dimension (Unit:mm)

Model	A B			3	(D	
wodel	Min.	Max.	Min.	Max.	Min.	Max.	Min.
SMD300L-24V	6.73	7.98	4.80	5.44	0.60	1.30	0.30

Dimensions & Marking







Recommended Pad Layout (mm)

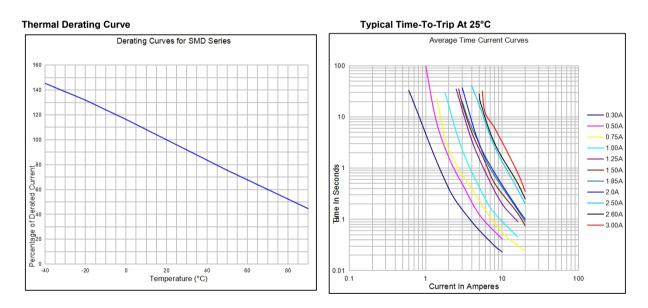
Termination Pad Characteristics

Tin-plated Nickel-Copper Terminal pad materials : Terminal pad solderability :

Meets EIA specification RS186-9E and ANSI/J-STD-002 Category 3.

Rework

Use standard industry practices, the removal device must be replaced with a fresh one.



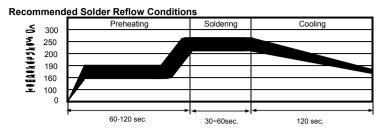
🕑 WARNING:

Use PPTC beyond the maximum ratings or improper use may result in device damage and possible electrical arcing and flame.

PPTC are intended for protection against occasional over current or over temperature fault conditions and should not be used when repeated fault conditions or prolonged trip events are anticipated. Device performance can be impacted negatively if devices are handled in a manner inconsistent with recommended electronic, thermal, and mechanical procedures for electronic components.

Use PPTC with a large inductance in circuit will generate a circuit voltage (L di/dt) above the rated voltage of the PPTC. Avoid impact PPTC device its thermal expansion like placed under pressure or installed in limited space. Contamination of the PPTC material with certain silicon based oils or some aggressive solvents can adversely impact the performance of the devices. PPTC SMD can be cleaned by standard methods. Requests that customers comply with our recommended solder pad layouts and recommended reflow profile. Improper board layouts or reflow profile could negatively impact solderability performance of our devices.

SMD300L-24V

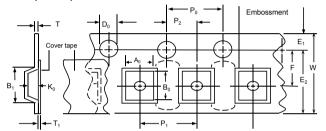


- Recommended reflow methods : IR, vapor phase oven, hot air oven. Devices are not designed to be wave soldered to the bottom side
- of the board.
- Recommended maximum paste thickness is 0.25 mm (0.010 inch).
- Devices can be cleaned using standard method and solvents. Note : If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

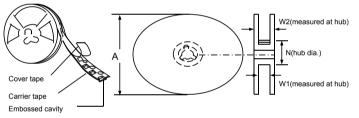
Tape And Reel Specifications (mm)

Governing Specifications	EIA 481-2
W	16.0 ± 0.3
P ₀	4.0 ± 0.10
P ₁	8.0 ± 0.10
P ₂	2.0 ± 0.05
<u>A</u> ₀	5.70 ± 0.10
B ₀	8.00 ± 0.10
B₁max.	12.1
D ₀ F	1.5 + 0.1, -0
F	7.5 ± 0.05
E ₁	1.75 ± 0.10
E ₂ min.	14.25
Tmax.	0.6
T₁max.	0.1
K ₀	0.80 ± 0.1
Leader min.	390
Trailer min.	160
Reel Dimensions	
A max.	178
N min.	60
W ₁	16.4 + 2.0, -0.0
W ₂ max.	22.4

EIA Tape Component Dimensions



EIA Reel Dimensions



- Storage And Handling Storage conditions : 40°C max, 70% R.H.
- Devices may not meet specified performance
- if storage conditions are exceeded.

300L	Tape & Reel Quantity
Hold	
Current	2,000 pcs/reel
3.00A	
	Current

Tape & reel packaging per EIA481-1

Labeling Information

Sea & Land Electronic Corp.
HF (Pb) RoHS
Model:
Part no.:
Spec.:
Lot no.:
Q'ty:
倉儲: 密封! 溫度: 18~33℃/濕度: 30~60% A

单击下面可查看定价,库存,交付和生命周期等信息

>>SEA-LAND(台湾陆海)